

- [illegible]

	U	I	Inventor	Document	Issue	P	Title	Current	Current	K	Retrieval	S	C	P	Q	Image	Def
1			Kinsman, La	US 2004016	2004	13	Bumped die and wire bonded board-on	257/737	257/E21.5		P	P	P	P	P		US 200401
2			Kinsman, L	US 668289	2004	12	Methods for bumped die and wire bond	438/61	257/108;		P	P	P	P	P		US 66828
3			Kinsman, La	US 2004016	2004	13	Bumped die and wire bonded board-on	257/20	257/E21.5		P	P	P	P	P		US 200401
4			Funaba, Sei	US 200500	2005	91	Stacked memory, memory module and	365/63	365/51		P	P	P	P	P		US 20050
5			Huang, Chi	US 200500	2005	11	Fabrication method of semiconductor	438/80			P	P	P	P	P		US 20050
6			Tsai, Chung	US 200500	2005	18	Window ball grid array semiconductor	257/73			P	P	P	P	P		US 20050
7			Tsai, Chung	US 200500	2005	16	Window ball grid array semiconductor	257/737	438/613		P	P	P	P	P		US 20050
8			Wang, Sung	US 200500	2005	6	Flip chip stacked package	257/778			P	P	P	P	P		US 20050
9			Khan, Reza	US 200500	2005	3	Enhanced die-up ball grid array and m	257/773			P	P	P	P	P		US 20050
10			Huang, Chi	US 200402	2004	113	Flash-preventing window ball grid arra	257/73			P	P	P	P	P		US 20040